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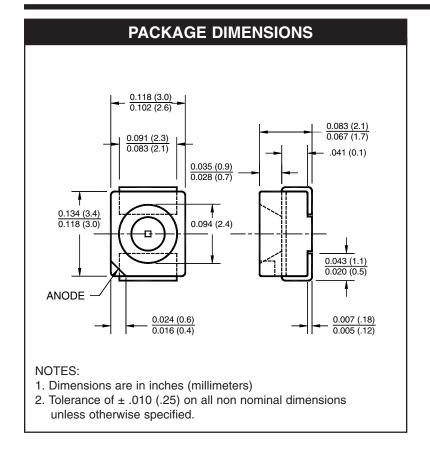
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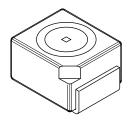
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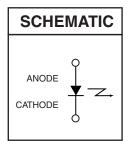
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## SURFACE MOUNT INFRARED LIGHT EMITTING DIODE

**QEB441** 







#### **DESCRIPTION**

The QEB441 is a 730 nm AlGaAs LED encapsulated in a PLCC-2 package.

#### **FEATURES**

- λ= 730 nm
- Chip Material: AlGaAs double heterojunction
- Surface Mount PLCC-2 package
- Wide Emission Angle, 120°
- High Power
- Tape and Reel option: .TR



# SURFACE MOUNT INFRARED LIGHT EMITTING DIODE

### **QEB441**

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Unit				
Operating Temperature	T <sub>OPR</sub>	-55 to +100	°C				
Storage Temperature	T <sub>STG</sub>	-55 to +100	°C				
Soldering Temperature (Flow)(2,3)	T <sub>SOL</sub>	260 for 10 sec	°C				
Continuous Forward Current	I <sub>F</sub>	100	mA				
Peak Forward Current <sup>(4)</sup>	I <sub>FP</sub>	1	A				
Reverse Voltage	V <sub>R</sub>	5	V				
Power Dissipation(1)	P <sub>D</sub>	180	mW				

#### **NOTES**

- 1. Derate power dissipation linearly TBD mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Pulse conditions: tp = 100  $\mu$ s, T = 10 ms.

ELECTRICAL / OPTICAL CHARACTERISTICS (TA =25°C)								
PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
Forward Voltage	$I_F = 10 \text{ mA}, \text{ tp} = 20 \text{ ms}$		_	_	2.0	V		
	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	V <sub>F</sub>	_	2.1	_			
	$I_F = 500 \text{ mA}, \text{ tp} = 1 \text{ ms}$	''	_	3.9	4.5			
	$I_F = 1A$ , tp = 100 $\mu$ s		_	5.5	_			
Emission Angle	I <sub>F</sub> = 100 mA	201/ <sub>2</sub>	_	120	_	%		
Reverse Leakage Current V <sub>R</sub> = 5 V		I <sub>R</sub>	_	_	10	μΑ		
Peak Emission Wavelength	I <sub>F</sub> = 100 mA	$\lambda_{P}$	710	730	750	nm		
Spectral Bandwidth	I <sub>F</sub> = 100 mA	$\Delta \lambda$	_	25	_	nm		
Radiant Intensity	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$		2	3	6	mW/sr		
	$I_F = 500 \text{ mA, tp} = 1 \text{ ms}$	le	9	14	28			
	$I_F = 1 \text{ A, tp} = 100 \ \mu\text{s}$		16	24	48			
Response Time	$I_F = 10 \text{ mA}, \text{ tp} = 100 \ \mu\text{s}, \text{ T} = 10 \text{ ms}$	t <sub>r,</sub> t <sub>f</sub>	_	_	100	ns		



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### **QEB441**

Fig.1 Relative Radiant Intensity vs. Input Current

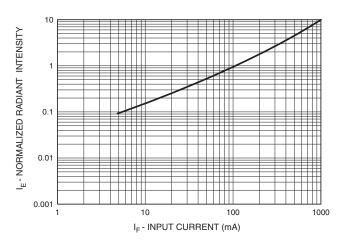


Fig.2 Forward Current vs. Forward Voltage

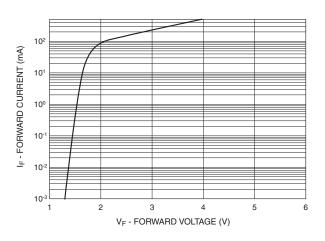


Fig.3 Radiation Diagram

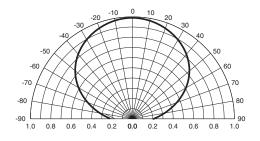


Fig.4 Forward Voltage vs. Ambient Temperature

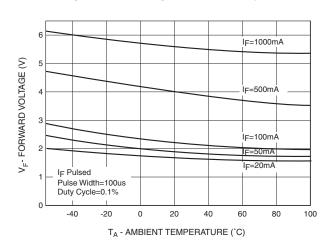
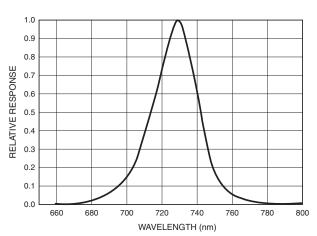


Fig.5 Spectral Response





## SURFACE MOUNT INFRARED LIGHT EMITTING DIODE

**QEB441** 

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